CLAIMS

[Claim 1] A resin sheet, comprising:

a base sheet containing a polystyrene-based resin; and

a surface layer containing a conductive material and a thermoplastic resin, laminated on at least one surface of the base sheet,

wherein a durometer D-type surface hardness measured on the basis of JIS-K-7215 is 67 or more and less than 80.

[Claim 2] The resin sheet according to claim 1,

wherein when performing dynamic viscoelasticity measurement, a storage modulus E'1 at 25°C is 1.0×10^8 Pa or more and 1.0×10^{10} Pa or less, and a storage modulus E'2 at Loss Tangent Peak Temperature + 20°C is 1.0×10^6 Pa or less.

[Claim 3] The resin sheet according to claim 1 or 2,

wherein the base sheet contains one or more types of resins of a general-purpose polystyrene resin and an impact-resistant polystyrene resin in a total of 50% by mass or more, on the basis of a total amount of a styrene-based resin.

[Claim 4] A resin sheet, comprising:

a base sheet containing a thermoplastic resin; and

a surface layer containing a conductive material and a thermoplastic resin, laminated on at least one surface of the base sheet,

wherein when performing dynamic viscoelasticity measurement, a storage modulus E'1 at 25°C is 1.0×10^8 Pa or more and 1.0×10^{10} Pa or less, and a storage modulus E'2 at Loss Tangent Peak Temperature + 20°C is 1.0×10^6 Pa or less.

[Claim 5] A container that is a compact of the resin sheet according

to any one of claims 1 to 4.

[Claim 6] A carrier tape that is a compact of the resin sheet according to any one of claims 1 to 4 and is provided with an accommodation portion capable of accommodating a commodity.

[Claim 7] An electronic component packaging, comprising:

the carrier tape according to claim 6;

an electronic component accommodated in the accommodation portion of the carrier tape; and

a cover film adhering to the carrier tape as a lid material.